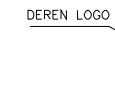




DATE CODE: X XX X X

YEAR (1~9) WEEK (01~52or53) DAY (1~7) SHIFT (DAY: D, NIGHT: N)

—PRODUCT NAME



DEREN LOGO

Country	1980	1985	1990	1995	2000
Japan	18.5	19.5	20.5	21.5	22.5
France	15.5	16.5	17.5	18.5	19.5
Germany	14.5	15.5	16.5	17.5	18.5
Italy	13.5	14.5	15.5	16.5	17.5
Spain	12.5	13.5	14.5	15.5	16.5
United Kingdom	11.5	12.5	13.5	14.5	15.5
Sweden	10.5	11.5	12.5	13.5	14.5
Canada	9.5	10.5	11.5	12.5	13.5
United States	8.5	9.5	10.5	11.5	12.5

R0.575

4X $\varnothing 0.80 \pm 0.05$
THOUGH HOLES

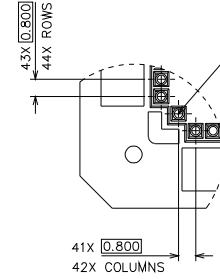
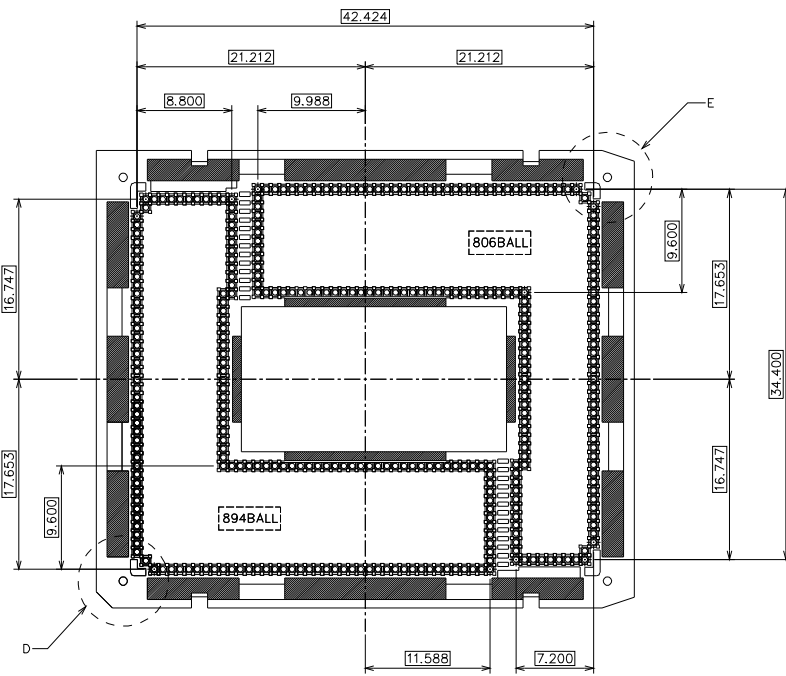
$\varnothing$	0.10	A	B	C
---------------	------	---	---	---

4.35±0.05
FULL HSG THICKNESS

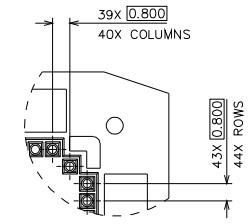
SOCKET	J1	J2
LGA1700-0	11.0	6.0

TABLE B:

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			INITIAL RELEASE	07/06'2022	Robin



DETAIL D
SCALE 2:1



DETAIL E
SCALE 2:1

DIM	TOL	DIM	TOL
x.	$\pm 0,35$	x.	$\pm 2'$
.x	± 0.30	.x	$\pm 1'$
.xx	± 0.25		



DEREN

SHENZHEN DEREN ELECTRONIC CO., LTD

CUSTOMER DRAWING

	DESIGN:	DATE:
--	---------	-------

DESIGN:	Robin

CHECK:	
--------	--

APPROVAL	
----------	--

DRAW NO.
SC2208101

--	--

REV.	A
------	---

DATE	TITLE: SOCKET-V LGA1700 ASSEMBLY
------	----------------------------------

en / release	B / N: SEE TABLE A
--------------	-------------------------------

07/06 2022	P/N:	SEE TABLE A

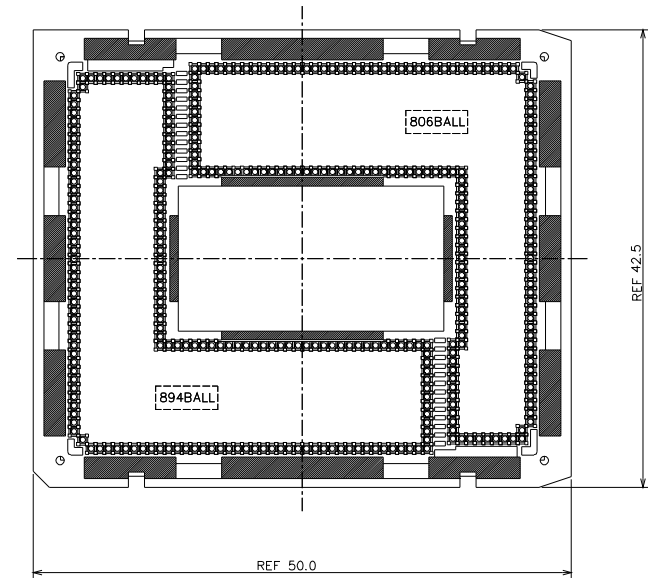
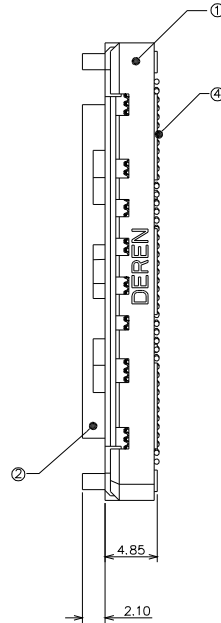
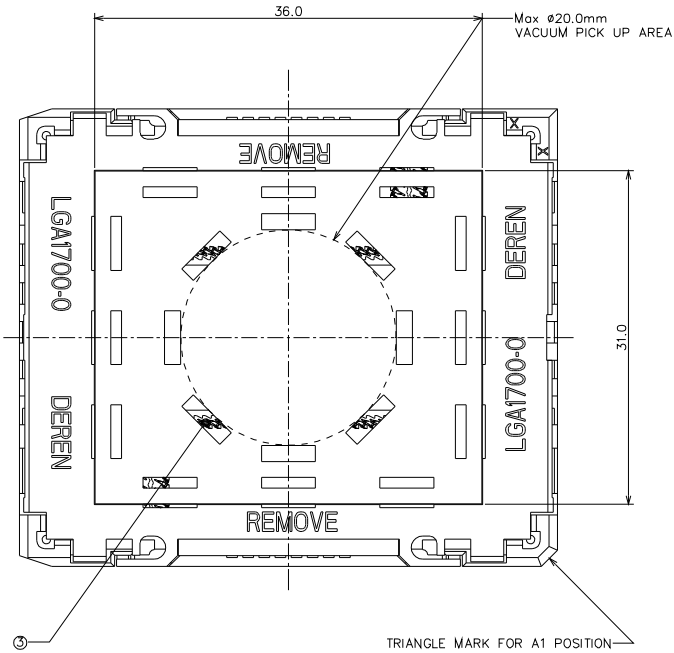
SHEET: 2/6

SCALE:	1:1	UNIT:	mm
--------	-----	-------	----

	CONVERT	INT	CONV.	INT

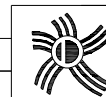
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			INITIAL RELEASE	07/06'2022	Robin

HF
Halogen Free



ASSEMBLY COMPONENT LIST		
ITEMS	PART NAME	QT'Y
1	HOUSING	1
2	PNPCAP	1
3	CONTACT	1700
4	BALL	1700
5	HARD TRAY	1/15

DIM	TOL	DIM	TOL
x.	±0,35	x.	±2'
.x	±0.30	.x	±1'
.xx	±0.25		



DEREN
SHENZHEN DEREN ELECTRONIC CO., LTD

DRAW NO.
SC2208101

REV. A

CUSTOMER DRAWING		DATE
DESIGN:	Robin	07/06'2022
CHECK:		
APPROVAL:		

TITLE: SOCKET-V LGA1700 ASSEMBLY	
P/N:	SEE TABLE A
SHEET: 3/6	
SCALE: 1:1	UNIT: mm

HF

Halogen Free



REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			INITIAL RELEASE	07/06'2022	Robin

NOTES :

PRODUCT MUST MEET CONTROLLED SUBSTANCES SPEC. ROHS 2.0

1. MATERIAL :

1.1 HOUSING&PNPCAP: LCP, UL94V-0, COLOR: BLACK.

1.2 CONTACTS: COPPER ALLOY.

1.3 BALL: $\varnothing 0.50 \pm 0.02 \text{mm}$ Sn/Ag/Cu.

1.4 TRAY: PS, UL94V-0, COLOR: BLACK.

2. FINISH:

CONTACT: Au PLATING ON CONTACT AREA (SEE TABLE A).

[50u"] MIN. NICKEL UNDERPLATING OVERALL.

3. Ⓢ CTF DIMENSION(CRITICAL TO FUNCTION) BY INTEL:

4. PRODUCT MUST MEET THE SPECIFICATION(DP-PS-0128)

TABLE A:

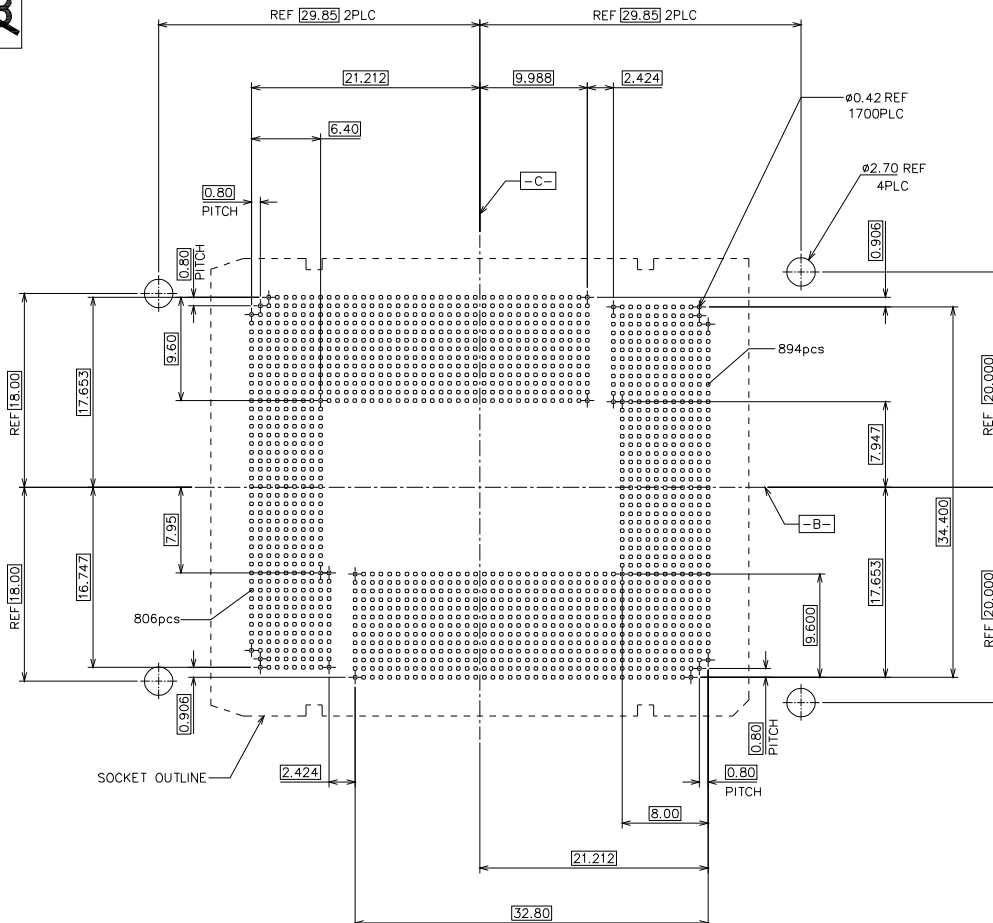
3	LGA1700	56ZZ05-003H	TBD	CONTACT	Au: 30u", Ni: 50u"min.
				SOLDER BALL	$\varnothing 0.50 \pm 0.02 \text{mm}$ Sn/Ag/Cu
				PNPCAP	UL94V-0, BLACK
2	LGA1700	56ZZ05-002H	TBD	CONTACT	Au: 15u"min, Ni: 50u"min.
				SOLDER BALL	$\varnothing 0.50 \pm 0.02 \text{mm}$ Sn/Ag/Cu
				PNPCAP	UL94V-0, BLACK
1	LGA1700	56ZZ05-001H	TBD	CONTACT	GOLD FLASH 1u"min, Ni: 50u"min.
				SOLDER BALL	$\varnothing 0.50 \pm 0.02 \text{mm}$ Sn/Ag/Cu
				PNPCAP	UL94V-0, BLACK
ITEM NO.	TYPE	DEREN P/N	CUSTOMER P/N	COMPONENT	SPECIFICATION



DEREN

SHENZHEN DEREN ELECTRONIC CO., LTD

DIM	TOL	DIM	TOL		SHENZHEN DEREN ELECTRONIC CO., LTD						
x.	±0,35	x.	±2'		CUSTOMER DRAWING		DATE		TITLE: SOCKET-V LGA1700 ASSEMBLY		
.x	±0.30	.x	±1'		DRAW NO. SC2208101	DESIGN:	Robin	07/06'2022	P/N: SEE TABLE A		
.xx	±0.25					CHECK:			SHEET: 4/6 		
				REV. A	APPROVAL:			SCALE: 1:1		UNIT: mm	



REFERENCE PATTERN LAYOUT



A

A

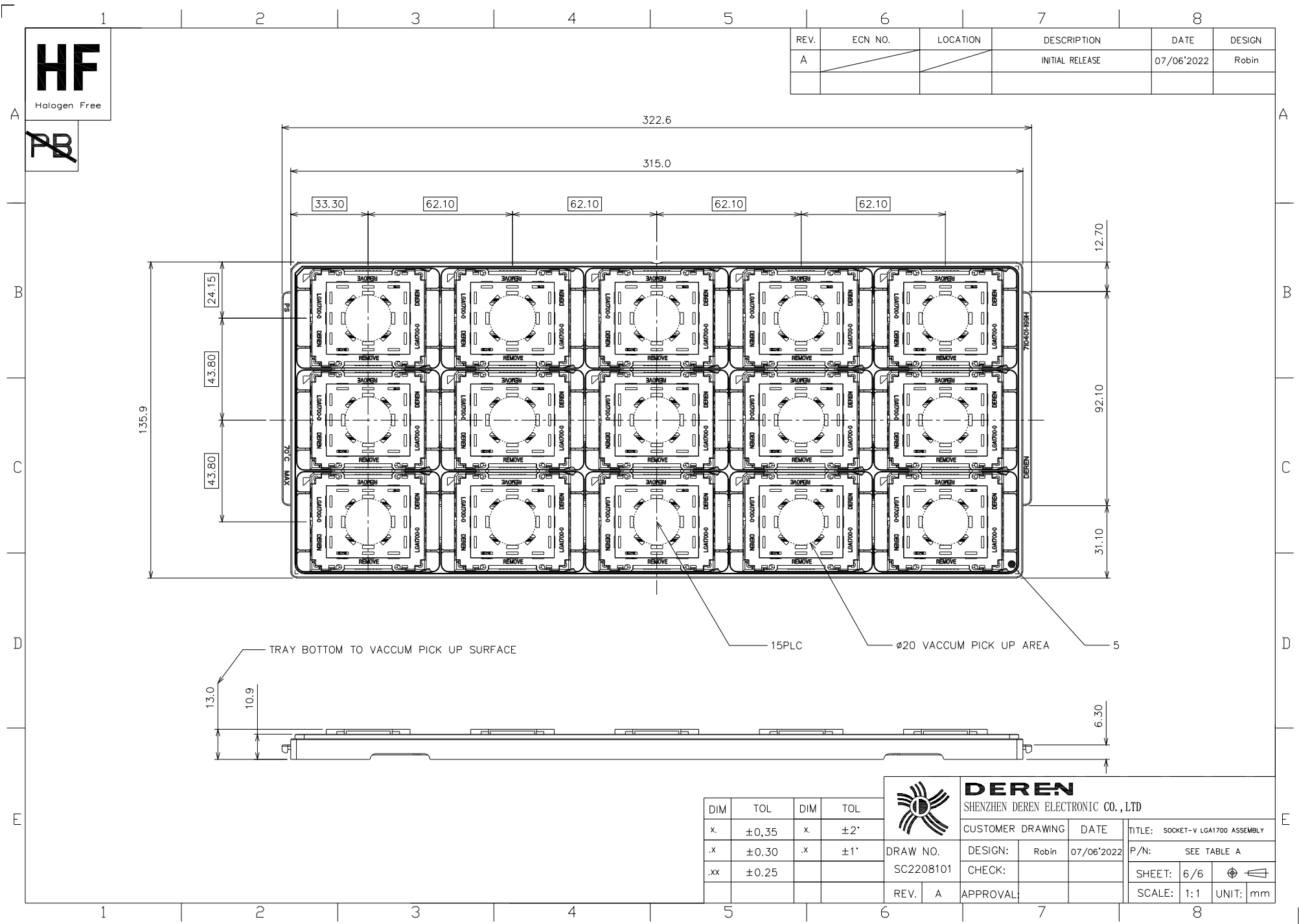
B

- C

D

1-1	UNIT.
-----	-------

E



REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			INITIAL RELEASE	07/06'2022	Robin

DIM	TOL	DIM	TOL
x.	±0.35	x.	±2'
.x	±0.30	.x	±1'
.xx	±0.25		



DEREN
SHENZHEN DEREN ELECTRONIC CO., LTD

DRAW NO.
SC2208101

REV. A

CUSTOMER DRAWING	DATE
DESIGN: Robin	07/06'2022
CHECK:	
APPROVAL:	

TITLE:	SOCKET-V LGA1700 ASSEMBLY
P/N:	SEE TABLE A
SHEET:	6/6
SCALE:	1:1
UNIT:	mm